I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted via the Office electronic filing system in accordance with \S 1.6(a)(4).

Dated: January 3, 2011

Electronic Signature for Richard J. Botos: /Richard J. Botos/

Docket No.: ROUND 3.0-131 DIV III (PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Nathan R. Brown

Application No.: 10/715,267 Group Art Unit: 1716

Filed: November 17, 2003 Examiner: S. MacArthur

For: METHODS FOR POLISHING

SEMICONDUCTOR DEVICE STRUCTURES BY DIFFERENTIALLY APPLYING PRESSURE TO SUBSTRATES THAT CARRY THE SEMICONDUCTOR DEVICE

STRUCTURES

MS RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

It is respectfully requested that the references listed on the enclosed form be made of record and considered with respect to the above-referenced U.S. patent application. A copy of each reference which is not a U.S. patent or patent application is enclosed. Submission of the present Information Disclosure Statement should not be taken as an admission that the cited references are legally available prior art or that the same are pertinent or material.

In the event that any fee is due in connection with the present Information Disclosure Statement, the Commissioner is hereby authorized to charge the same to our Deposit Account No. 12-1095.

Dated: January 3, 2011

Respectfully submitted, Electronic signature: /Richard J. Botos/ Richard J. Botos Registration No.: 32,016 LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP 600 South Avenue West Westfield, New Jersey 07090 (908) 654-5000 Attorney for Applicant(s)

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